

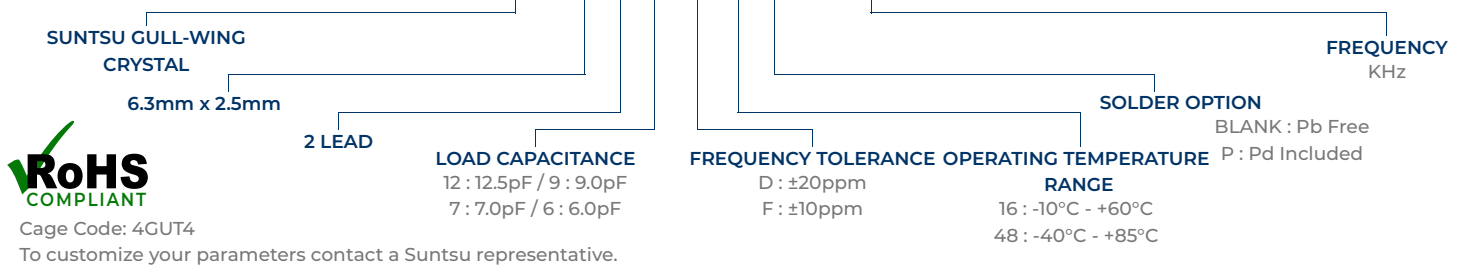
| Features |
|---|
| <ul style="list-style-type: none"> ±20ppm (Tolerance) Available Gull-Wing Leads For SMD Type Reflow Capable Tape and Reel |

| Applications |
|---|
| <ul style="list-style-type: none"> Real Time Clock Measurement instruments Wireless Applications |



Part Numbering Guide

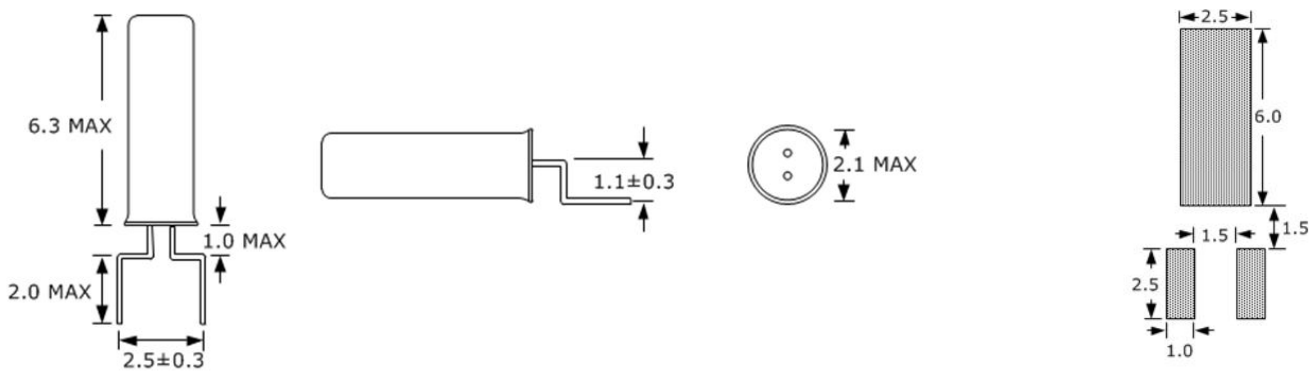
SWG 66 2 12 D 48 P - 32.768KHz



| Electrical Parameters | Units | Minimum | Typical | Maximum | Remarks |
|-------------------------------|--------------------|---------|---------|---------|---------------------------------------|
| Frequency Range | KHz | | 32.768 | | |
| Frequency Tolerance at +25°C | ppm | -20 | | +20 | See part numbering guide for options. |
| Frequency Stability v's Aging | ppm | -3 | | +3 | First year @ +25°C. |
| Frequency Coefficient (β) | ppm/T ² | -0.040 | -0.034 | -0.028 | |
| Operating Temperature | °C | -40 | | +85 | See part numbering guide for options. |
| Turnover Temperature | °C | +20 | +25 | +30 | |
| Storage Temperature | °C | -55 | | +125 | |
| Load Capacitance | pF | 6 | | 12.5 | See part numbering guide for options. |
| Shunt Capacitance | pF | | 1.5 | | |
| Drive Level | μW | | | 1 | |
| Insulation Resistance | MΩ | 500 | | | @ 100VDC ± 15V. |
| Equivalent Series Resistance | kΩ | | | 50 | |

Outline Drawing & Recommended Land Pattern

All dimensions are in millimeters (mm) unless otherwise noted. Drawings are not to scale.



| Environmental Specifications | | Mechanical Specifications | |
|------------------------------|--|------------------------------|---------------------------------------|
| Temperature Cycling | MIL-STD-883, Method 1010, Condition B | Mechanical Shock | MIL-STD-202, Method 213, Condition B |
| Fine Leak Test | MIL-STD-883, Method 1014, Condition A | Vibration | MIL-STD-883, Method 2007, Condition A |
| Gross Leak Test | MIL-STD-883, Method 1014, Condition C | Resistance to Soldering Heat | MIL-STD-202, Method 210, Condition B |
| Moisture Resistance | MIL-STD-883, Method 1004 | Resistance to Solvents | MIL-STD-202, Method 215 |
| Moisture Sensitivity | Hermetically Sealed, MSL=N/A: Not Applicable | Solderability | MIL-STD-883, Method 2003 |

